

INFORMATION DISCLOSURE CITATION
(Use several sheets if necessary)

ATTY-DOCKET NO.
EN9-97-075USS

SERIAL NO.
LJ

Francis J. Downes et al.
FILING

#2 IDS
GROUP 5303

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	5,072,075	12/1991	Lee et al.			
	5,121,190	6/1992	Hsiao et al.			
	5,483,421	1/1996	Gedney et al.			
	5,574,630	11/1996	Kresge et al.			
	5,615,087	3/1997	Wieloch			
	5,798,563	8/1998	Feilchenfeld et al.			
	5,894,173	4/1999	Jacobs et al.			
	5,900,675	5/1999	Appelt et al.			
	4,882,454	11/1989	Peterson et al.			
	5,982,630	11/1999	Bhatia			
	5,926,377	7/1999	Nakao et al.			

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
	9-232376	9/1997	Japan				
	10-209347	8/1998	Japan				
	11-87560	3/1999	Japan				
	2000-22071	1/2000	Japan				
	6-112271	4/1994	Japan				

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

		IBM Technical Disclosure Bulletin, Vol. 32, No. 3B, August 1989, "MULTILAYER POLYMER SUBSTRATE FOR DIRECT CHIP ATTACHMENT."
		PROCESS CONSIDERATIONS IN THE FABRICATION OF TEFLON PRINTED CIRCUIT BOARDS, Light et al., 1994 Proceedings, 44 Electronic Components & Technology Conference, 5/94.

EXAMINER

DATE CONSIDERED

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

***EXAMINER:** Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.